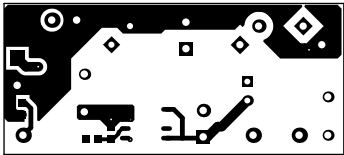
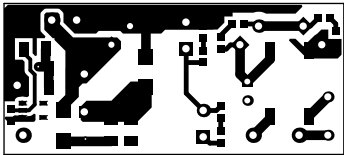


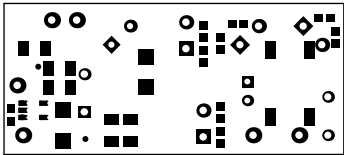
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11236	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #:		
PLOT NAME = Top Solder Mask	GENERATED : 8/12/2015 5:43:01 PM	TEXAS INSTRUMENTS	



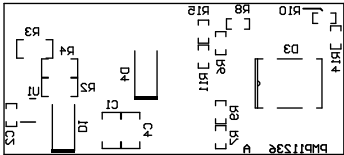
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11236	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #:		
PLOT NAME = Top Layer	GENERATED : 8/12/2015 5:43:02 PM	TEXAS INSTRUMENTS	



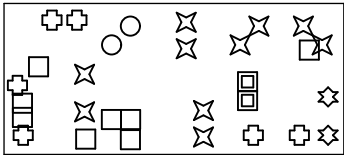
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11236	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #:		
PLOT NAME = Bottom Layer	GENERATED : 8/12/2015 5:43:02 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11236	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #:		
PLOT NAME = Bottom Solder Mask	GENERATED : 8/12/2015 5:43:03 PM	TEXAS INSTRUMENTS	

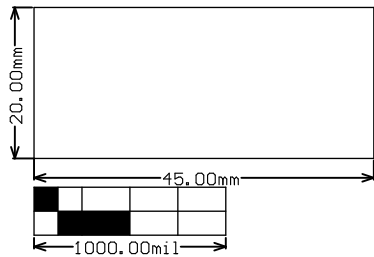


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11236	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #:		
PLOT NAME = Bottom Overlay	GENERATED : 8/12/2015 5:43:04 PM		TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
□	8	10.00mil (0.254mm)	PTH	Round
■	2	31.00mil (0.787mm)	PTH	Round
○	2	33.00mil (0.838mm)	PTH	Round
☆	2	37.40mil (0.950mm)	PTH	Round
✕	10	39.37mil (1.000mm)	PTH	Round
⊗	6	40.00mil (1.016mm)	PTH	Round
	30 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11236	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #:		
PLOT NAME = Drill Drawing	GENERATED : 8/12/2015 5:43:05 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11236	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #:		
PLOT NAME = Board Dimensions	GENERATED : 8/12/2015 5:43:05 PM	TEXAS INSTRUMENTS	

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